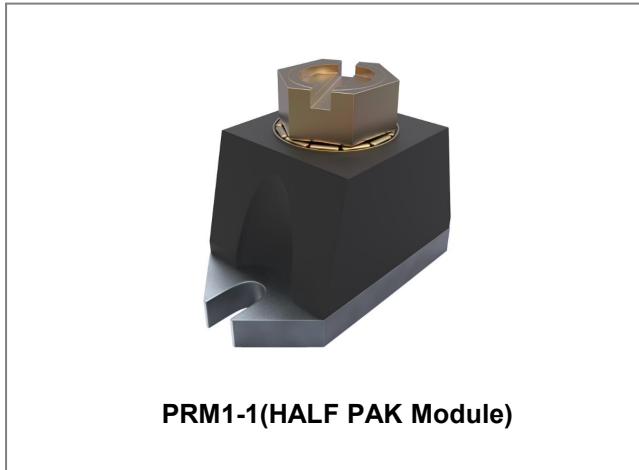


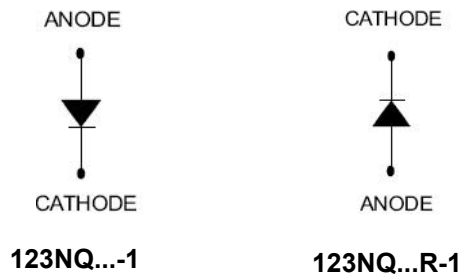
123NQ080/R-1 123NQ100/R-1 SCHOTTKY RECTIFIER



Features

- 175°C T_J operation
- Unique high power, Half-Pak module
- Replaces three parallel DO-5'S
- Easier to mount and lower profile than DO-5'S
- High purity, high temperature epoxy encapsulation for enhanced
- mechanical strength and moisture resistance
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Maximum Ratings:

Characteristics	Symbol	Condition	Max.		Units
			80	123NQ080(R)-1	
Peak Repetitive Reverse Voltage	V _{RRM}	-	80	123NQ080(R)-1	V
Working Peak Reverse Voltage	V _{RWM}		100	123NQ100(R)-1	
DC Blocking Voltage	V _R				
Average Forward Current	I _{F(AV)}	50% duty cycle @T _C =133°C, rectangular wave form	120		A
Peak One Cycle Non-Repetitive Surge Current	I _{FSM}	8.3 ms, half Sine pulse	2520		A
Non-Repetitive Avalanche Energy	E _{AS}	T _J =25°C, I _{AS} =1A, L=30mH	15		mJ
Repetitive Avalanche Current	I _{AR}	Current decaying linearly to zero in 1 μsec Frequency limited by T _J max. V _A =1.5×V _R typical	1		A

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop*	V _{F1}	@ 120A, Pulse, T _J = 25 °C @ 240A, Pulse, T _J = 25 °C	0.80 -	0.91 1.08	V
	V _{F2}	@ 120A, Pulse, T _J = 125 °C @ 240A, Pulse, T _J = 125 °C	0.61 -	0.74 0.88	V
Reverse Current*	I _{R1}	@V _R = rated VR T _J = 25 °C	0.001	3	mA
	I _{R2}	@V _R = rated VR T _J = 125 °C	1	40	mA
Junction Capacitance	C _T	@V _R = 5V, T _C = 25 °C f _{SIG} = 1MHz	2400	2650	pF
Max. Voltage Rate of Change	dv/dt	-	-	10,000	V/μs

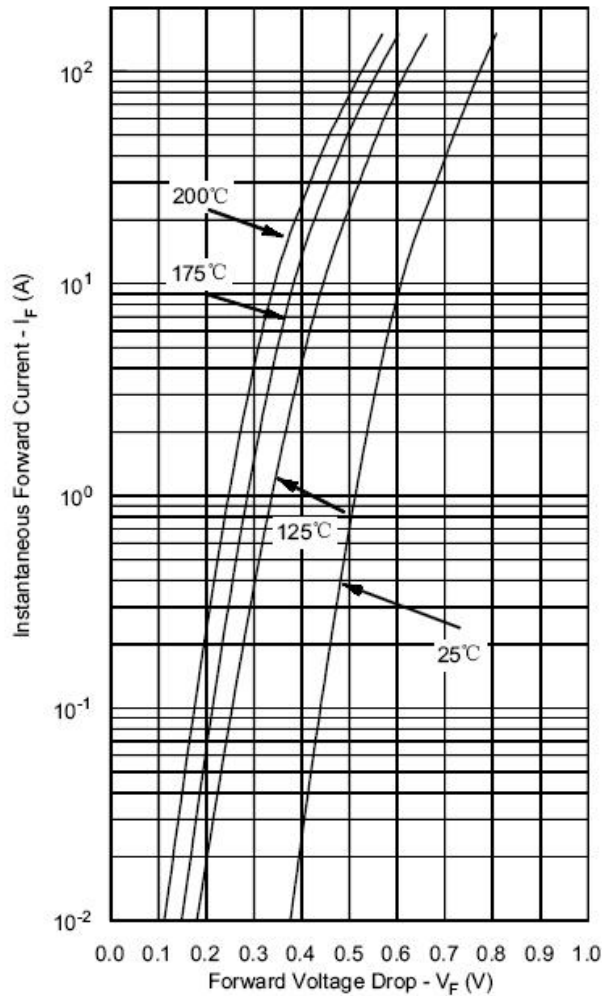
* Pulse width < 300 μs, duty cycle < 2%

Thermal-Mechanical Specifications:

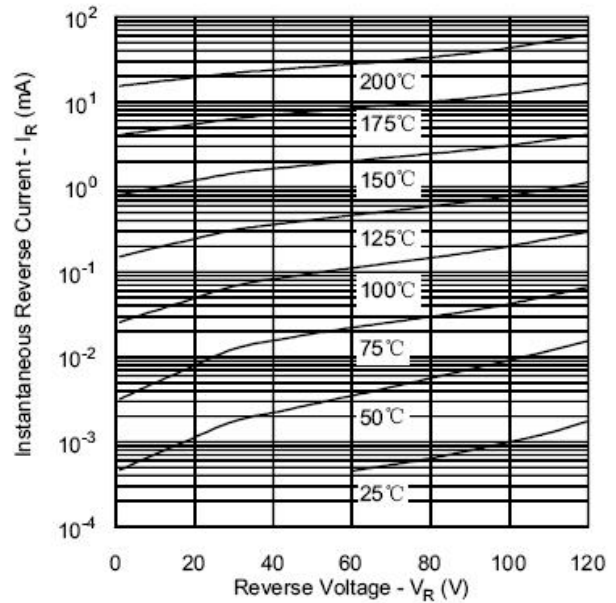
Characteristics	Symbol	Condition	Specification	Units	
Junction Temperature	T _J	-	-55 to +175	°C	
Storage Temperature	T _{stg}	-	-55 to +175	°C	
Typical Thermal Resistance Junction to Case	R _{θJC}	DC operation	0.40	°C/W	
Typical Thermal Resistance, case to Heat Sink	R _{θcs}	Mounting surface, smooth and greased	0.15	°C/W	
Mounting Torque	T _M	Non-lubricated threads	Mounting Torque	23(min) 29(max)	Kg-cm
			Terminal Torque	35(min) 46(max)	
Approximate Weight	wt	-	25.6	g	
Case Style	PRM1-1				

Ratings and Characteristics Curves

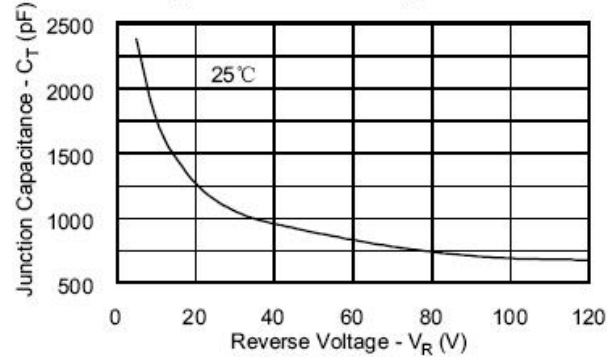
Typical Forward Characteristics



Typical Reverse Characteristics



Typical Junction Capacitance



Ordering Information

Device	Package	Shipping
123NQ SERIES	PRM1-1(Pb-Free)	27pcs/ box

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

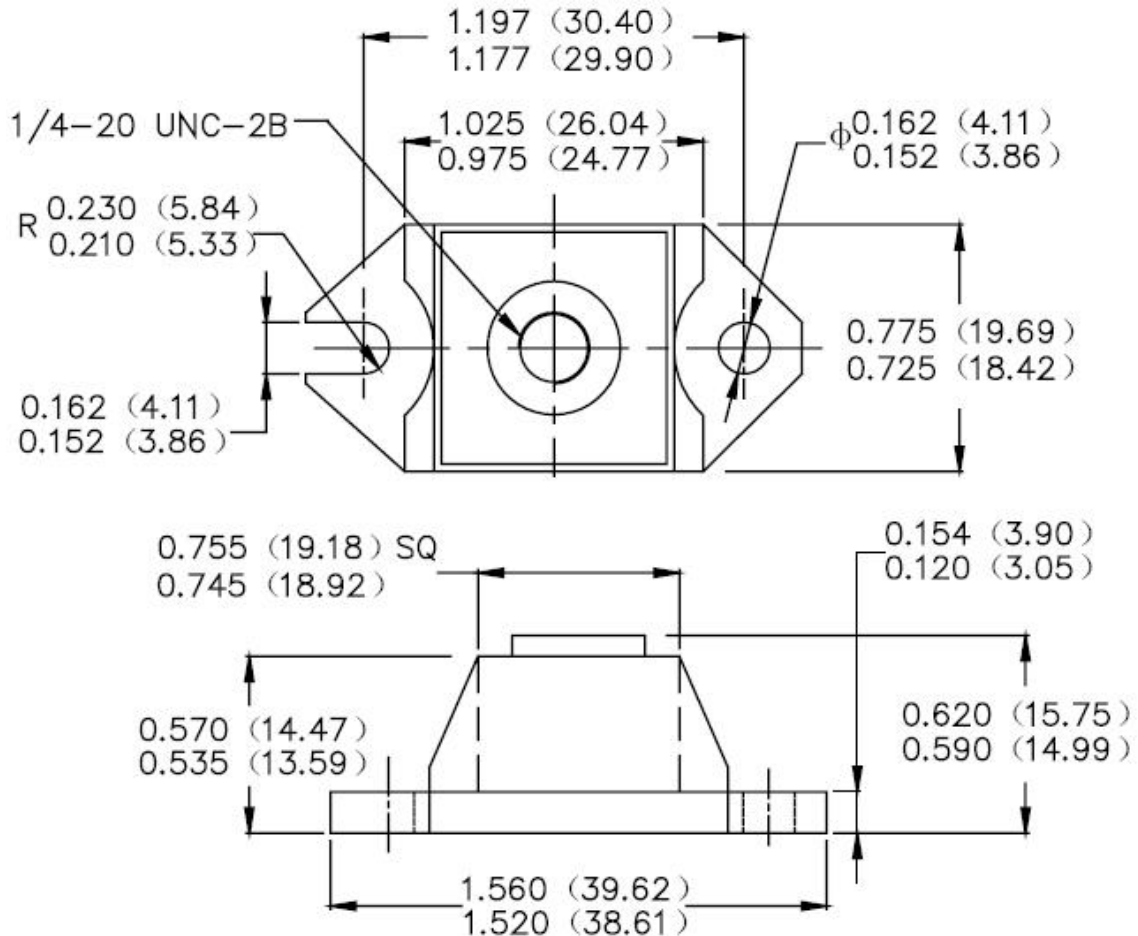


Where XXXX is YYWW

1st row SS YYWW
2nd row 123NQ080-1
SS = SS
YY = Year
WW = Week

Cautions: Molding resin
Epoxy resin UL:94V-0

Mechanical Dimensions PRM1-1 (Inches/Millimeters)



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